



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 09/829,161

Filed: April 9, 2001

For: METALLIZATION STRUCTURES
FOR SEMICONDUCTOR DEVICE
INTERCONNECTS, METHODS FOR
MAKING SAME, AND
SEMICONDUCTOR DEVICES
INCLUDING SAME

Confirmation No.: 8260

Examiner: H. Nguyen

Group Art Unit: 2812

Attorney Docket No.: 2269-3442.1US
(96-0428.01/US)

CERTIFICATE OF MAILING

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AMENDMENT

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Office Action mailed July 21, 2003, the three-month shortened statutory period for response to which expires on October 21, 2003.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 13 of this paper.